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November 8, 2000

Dr. Glenn A. Rinne  
Unitive Electronics, Inc.  
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Research Triangle Park, NC 27709-14584

RE: *A Process for Chip Scale Packaging Including the Integration of Wire  
Bonding and Solder Deposition on the Same Chip*  
Unitive Ref. EUI-00-006; Our File 9180-5

Dear Glenn:

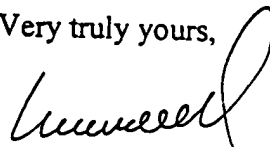
This letter will summarize our discussion of the above-identified disclosure on November 3, 2000.

The invention relates to an under bump metallurgy (UBM) structure and process that forms a UBM that includes at least two layers and a plated-on barrier metallurgy. Solder spheres are then placed on selected ones of the UBM and reflowed. This allows a common UBM structure to be used for wire bonding and flip chip joining to the same part, to allow, for example, an SRAM to be packaged on a microprocessor. This also can allow one UBM to be used for multiple tin-based solder compositions.

You indicated that prototypes may have been given to customers under non-disclosure agreements as early as but that no sale or offer for sale has yet occurred. Accordingly, U.S. and non-U.S. protection appears to be available. We will proceed to prepare a U.S. patent application for this invention. We will contact Dan Mis to obtain additional details.

Best regards.

Very truly yours,



Mitchell S. Bigel

MSB:sef

cc: Scott C. Hatfield, Esq.